

BYD Microelectronics Co., Ltd.

BF9035SNZ-M

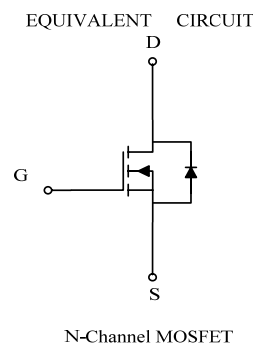
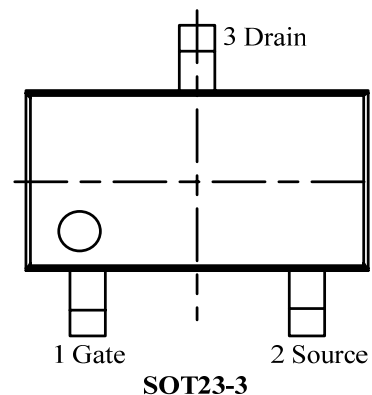
30V N-Channel MOSFET

General Description

The BF9035SNZ-M is a Single N-channel MOS Field Effect Transistor, which uses advanced trench technology to provide excellent $R_{DS(on)}$ and low gate charge. This is applied to electronic systems as a power switch.

Features

- $V_{DS}=30\text{ V}$
- $I_D=4\text{ A}$
- Low on-state resistance
 - $R_{DS(on)} < 65\text{ m}\Omega$ ($V_{GS}=10\text{ V}$, $I_D=2.0\text{ A}$)
 - $R_{DS(on)} < 80\text{ m}\Omega$ ($V_{GS}=4.5\text{ V}$, $I_D=2.0\text{ A}$)
 - $R_{DS(on)} < 95\text{ m}\Omega$ ($V_{GS}=3.0\text{ V}$, $I_D=2.0\text{ A}$)
- Lead Pb-free and Halogen-free



Absolute Maximum Ratings($T_C = 25^\circ\text{C}$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	30	V
I_D	Drain Current(continuous)at $T_C=25^\circ\text{C}$	4	A
I_{DM}	Drain Current (pulsed) (Note a)	16	A
V_{GS}	Gate-Source Voltage	± 12	V
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	2.0	W
T_J, T_{stg}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose	150	$^\circ\text{C}$

Ordering Information

Part Number	Package	Packaging
BF9035SNZ-M	SOT23-3	3000pcs Tape & Reel

**Electrical Characteristics ($T_c = 25^\circ\text{C}$)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DS}	Drain-source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$			1	μA
I_{GSS}	Gate-body Leakage Current	$V_{GS}=\pm 12\text{V}, V_{DS}=0\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.6	1	1.4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS}=3.0\text{V}, I_D=2\text{A}$		80	95	m Ω
		$V_{GS}=4.5\text{V}, I_D=2\text{A}$		65	80	
		$V_{GS}=10.0\text{V}, I_D=2\text{A}$		55	65	
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}, f=1\text{MHz}, V_{GS}=0\text{V}$		300		pF
C_{oss}	Output Capacitance			150		pF
C_{rss}	Reverse Transfer Capacitance			50		pF
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}, I_D=2\text{A},$ $V_{GS}=10\text{V}, R_G=4.7\Omega$ (Note b,c)		15		ns
t_r	Rise Time			20		ns
$t_{d(off)}$	Turn-off Delay Time			50		ns
t_f	Fall Time			12		ns
Q_g	Total Gate Charge	$V_{DS}=15\text{V}, I_D=4\text{A}, V_{GS}=4.5\text{V}$ (Note b,c)		3.8		nC
Q_{gs}	Gate-source Charge			0.8		nC
Q_{gd}	Gate-Drain Charge			1.4		nC
$V_{SD(*)}$	Forward On Voltage	$V_{GS}=0\text{V}, I_F=1\text{A}$		0.8	1	V

Notes

a: Repetitive Rating : Pulse width limited by maximum junction temperature

b: Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

c: Essentially independent of operating temperature

(*)Pulsed: Pulse duration

Caution: These values must not be exceeded under any conditions.

Typical characteristics (25°C unless noted)

Figure 1 Output Characteristics

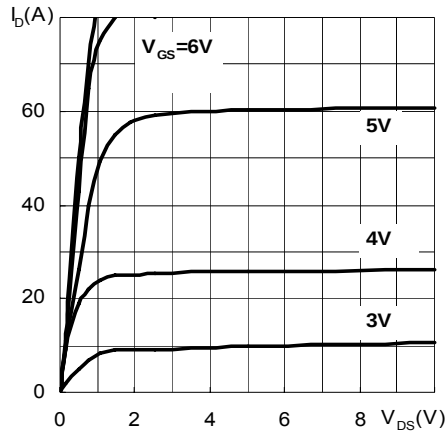


Figure 2 Transfer Characteristics

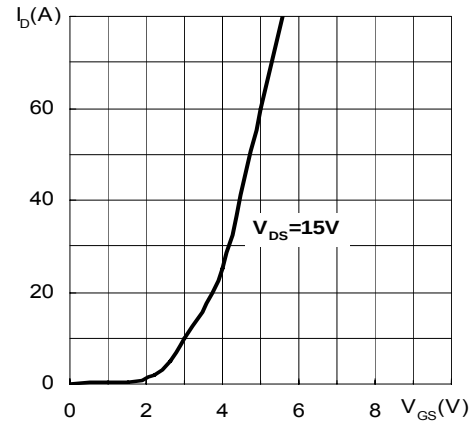


Figure 3 V_{th} vs. Temperature

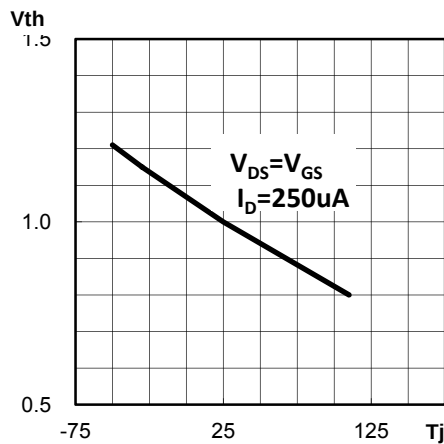


Figure 4 Normalized BV_{DSS} vs. Temperature

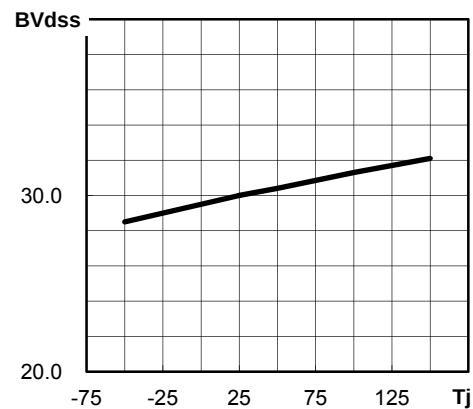


Figure 5 $R_{DS(on)}$ vs. Temperature

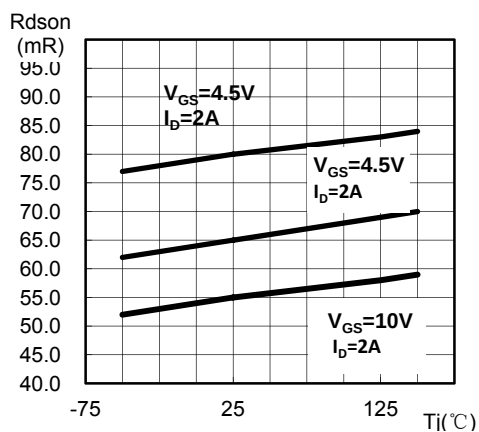


Figure 6 I_{GSS} vs Environment Temperature

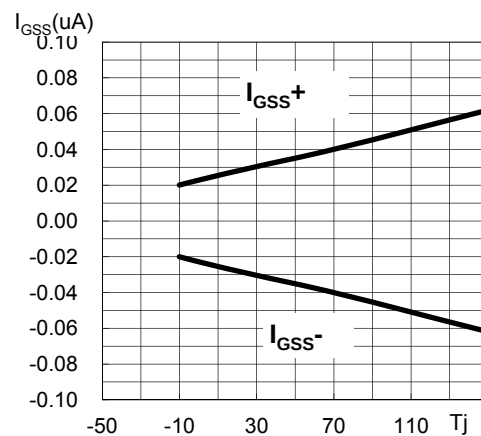


Figure 7 Capacitance

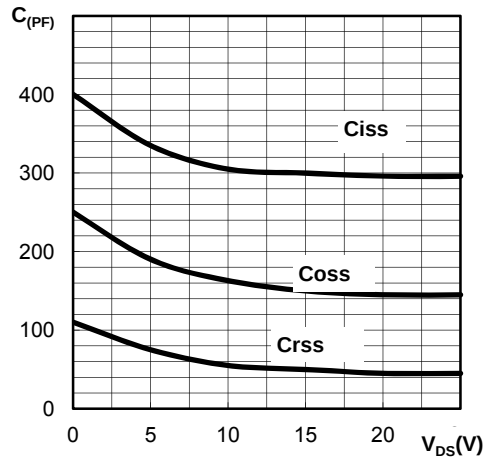


Figure 8 Gate Charge

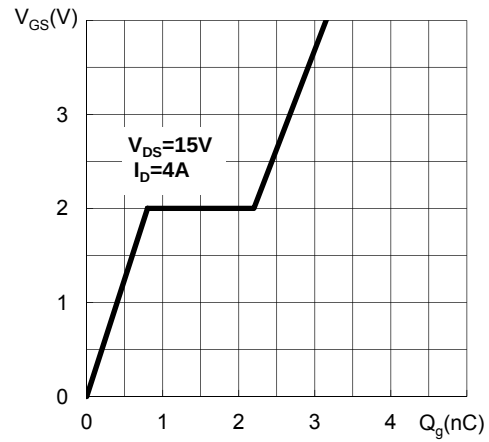


Figure 9 Safe Operating Area

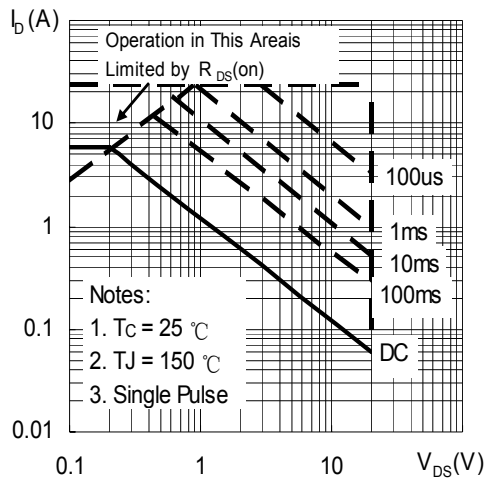


Figure 10 Maximum I_{DSS} vs. Case Temperature

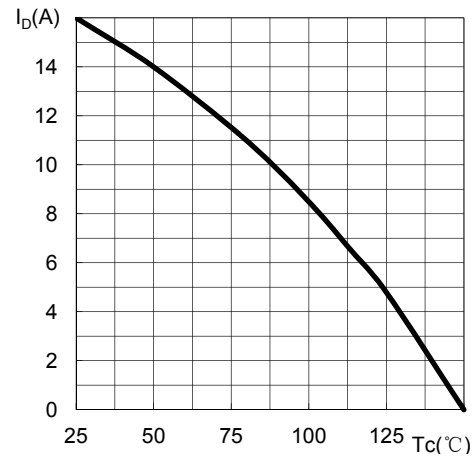


Figure 11 $R_{ds(on)}$ vs. V_{GS}

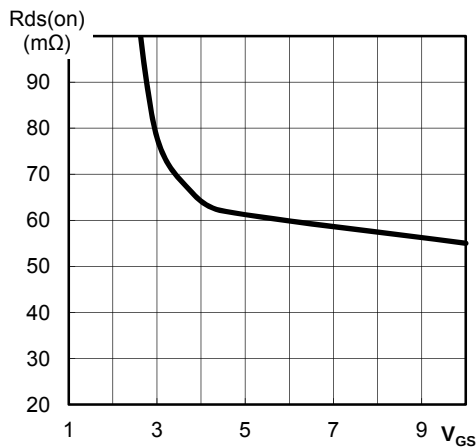


Figure 12 Gate-Current vs. Gate-Source Voltage

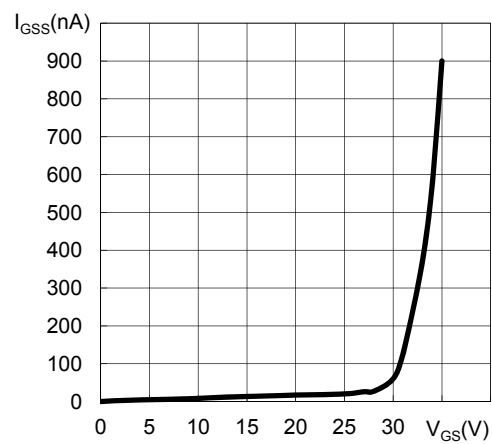
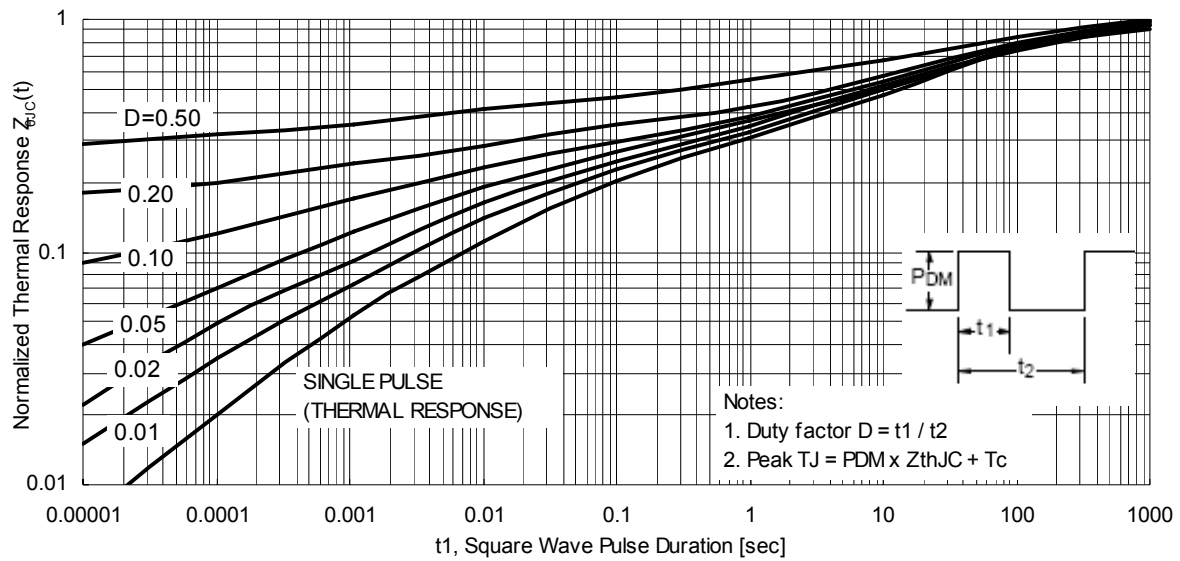
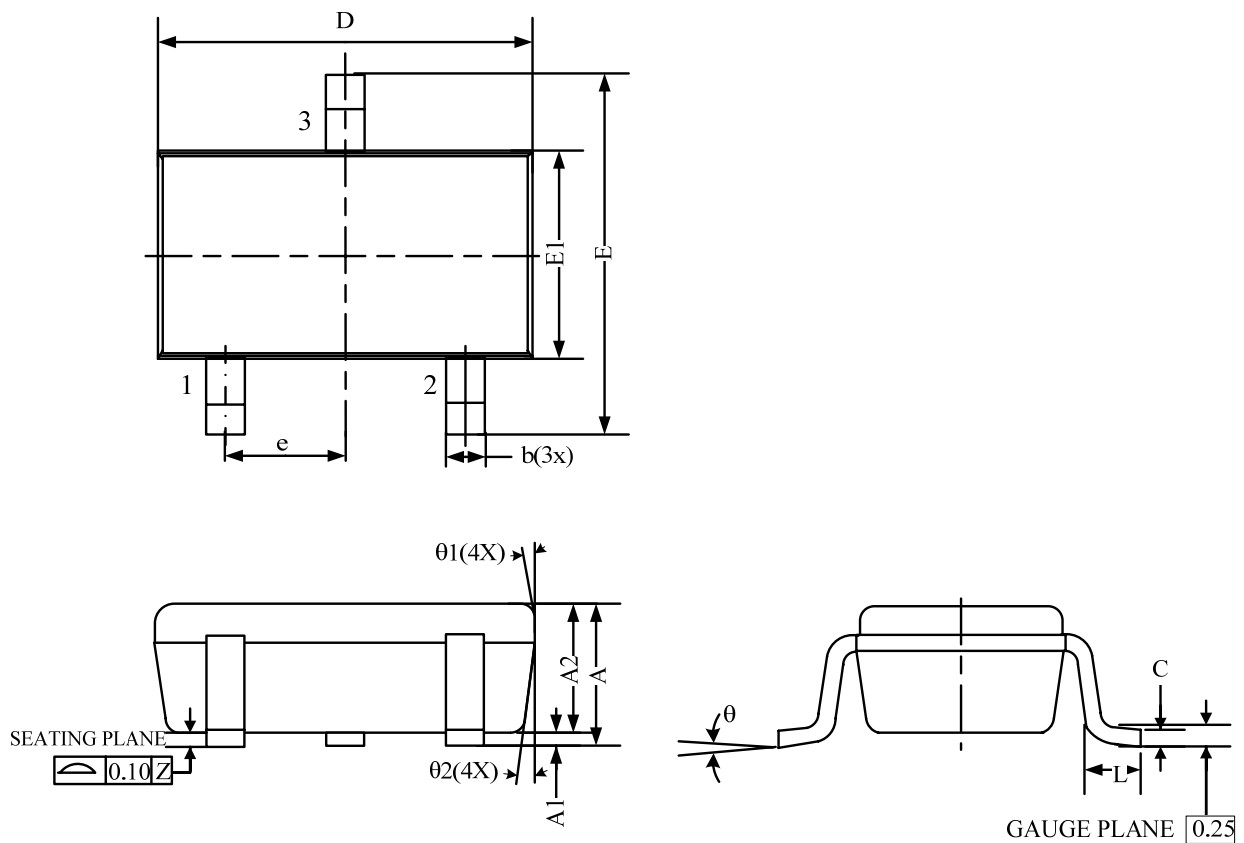


Figure 13 Maximum Transient Thermal Impedance



Package Drawing

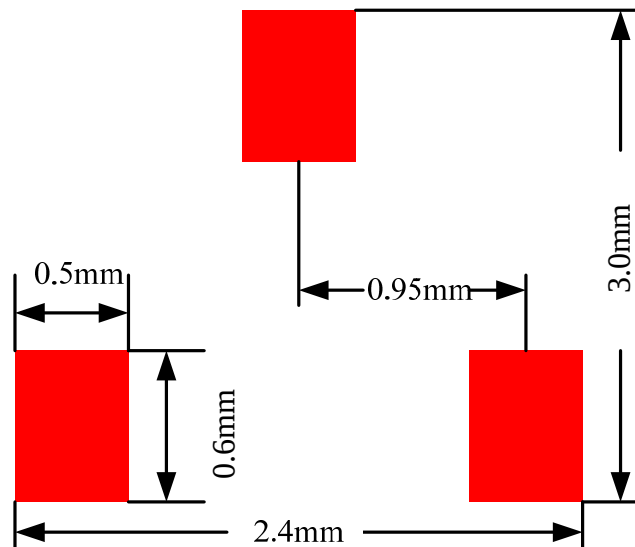


Dimensions

DIM.	A	A1	A2	b	C	D	E	E1	e	L	θ	θ1	θ2
mm	MIN.	1.00	0.03	1.00	0.30	0.10	2.80	2.60	1.50	0.95BSC	0.30	0°	5°
	NOM.	1.15	0.09	1.10	0.40	0.15	2.90	2.80	1.60		0.45	4°	6°
	MAX.	1.30	0.15	1.20	0.50	0.20	3.00	3.00	1.70		0.60	8°	7°

Note:

1. Dimension D does not include mold flash, protrusions or gate burrs. mold flash, protrusions or gate burrs shall not exceed 0.10mm per side.
2. Dimension E1 does not include inter-lead flash or protrusion. Inter-lead flash or protrusion shall not exceed 0.1mm per side.

PCB Layout Guide



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